

Properties of As-grown, Chemically Treated and Thermally Oxidized Surfaces of AlGaIn/GaN Heterostructure

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1. Introduction

The AlGaIn/GaN heterostructure has recently turned out to be an extremely important starting structure for fabrication of high-voltage/high-power HEMTs operating at microwave/millimeter-wave frequencies. Impressive frequency/power performances of devices as well as basic electrical properties of 2DEG at AlGaIn/GaN heterointerface have been reported by many workers, showing high potentials of these devices. However, properties of the surface of the AlGaIn/GaN heterostructure are not well understood in spite of the fact that any device processing step is initiated on this surface. Optimized control of the starting surface is an essentially important step for formation of stable Schottky gates and good ohmic contacts as well as for successful surface passivation.

In this paper, properties of as-grown, chemically treated and thermally oxidized surfaces of the AlGaIn/GaN heterostructure are systematically studied by x-ray photoelectron spectroscopy (XPS), Auger electron spectroscopy (AES), surface Raman spectroscopy, Hall-effect, capacitance-voltage and magneto-transport measurements.

2. Experimental

The structure of $\text{Al}_{0.25}\text{Ga}_{0.75}\text{N}/\text{GaN}$ heterostructure samples used in this study is shown in **Fig. 1**. The structure was grown by MOVPE on (0001) sapphire substrate. As a first step, properties of the air-exposed surface of the as-grown wafer were investigated. Then, in order to control the natural oxide layer on the air-exposed AlGaIn surface, the effect of the following three kinds of solutions for wet chemical treatments were investigated: (i) a KOH solution at room temperature (RT) for 1 min, (ii) an NH_4OH solution at 50°C for 15 min and (iii) an HF solution at RT for 15 min. Finally, in order further to compare surface chemistry as well as to explore possibilities of oxide surface passivation, AlGaIn surfaces were intentionally oxidized thermally at 900°C for 30 min in O_2 .

n- $\text{Al}_{0.25}\text{Ga}_{0.75}\text{N}$ (30 nm)
$\text{Al}_{0.25}\text{Ga}_{0.75}\text{N}$ (3 nm)
GaN (2 μm)
sapphire substrate

Fig. 1 sample structure.

3. Results and Discussion

Basic electrical properties of heterointerface

The Hall mobility and sheet carrier concentration of 2DEG formed at the AlGaIn/GaN heterointerfaces were $1200 \text{ cm}^2/\text{Vs}$ and $1.6 \times 10^{13} \text{ cm}^{-2}$ at RT, respectively. These are the typical values comparable to those reported in the literature. The Shubnikov de Hass oscillations were clearly observed above 4 T, indicating existence of 2DEG at the heterointerface. These results conformed that our AlGaIn/GaN heterostructure was of device quality with a high-quality AlGaIn toplayer, and worth while for further investigation.

Air-exposed surface of as-grown heterostructure

From the XPS measurements, a high-intensity O1s peak was detected on the air-exposed AlGaIn surface, being accompanied with broadening of Al, Ga, N and O core-level spectra. **Figure 2 (a)** shows the angle-resolved XPS spectra of the $\text{Al}2p$ level obtained from such a surface. All spectra had shoulders on the higher binding energy side. In particular, the spectrum obtained at an escape angle of 10° exhibited a peak position very close to that of the Al-O bond in the Al_2O_3 phase. A similar feature appeared in the $\text{Ga}3d$ core-level. Judging from the energy positions of the Al-O bond in $\text{Al}2p$ and the Ga-O bond in $\text{Ga}3d$, the air-exposed surface was covered with a natural oxide layer consisting of the Al_2O_3 and Ga_2O_3 components.

The XPS integrated intensity ratios of O1s to N1s ($\text{O}1s/\text{N}1s$), $\text{Al}2p$ to N1s ($\text{Al}2p/\text{N}1s$) and $\text{Ga}3d$ to N1s ($\text{Ga}3d/\text{N}1s$) are summarized in **Fig. 2 (b)** as a function of the escape angle. The O and Al components rapidly increased as the escape angle was decreased, indicating that the Al_2O_3 component is dominant in the natural oxide layer. From a detailed analysis, the thickness of the natural oxide layer was estimated to be 0.4-0.6 nm with the Al_2O_3 to Ga_2O_3 composition ratio of 2.3-4.0.

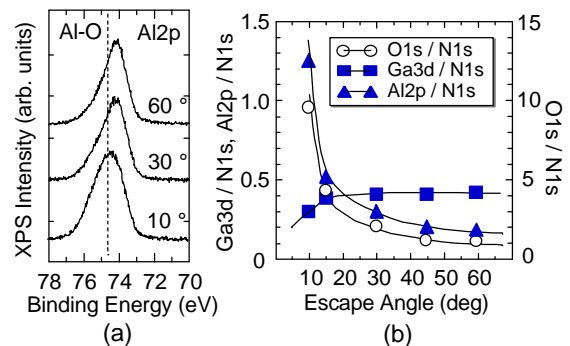


Fig. 2 (a) Angle-resolved XPS spectra and (b) integrated intensity ratios on air-exposed surface.

Effects of chemical treatments

In order to remove the natural oxide layer from the air-exposed surface, three kinds of chemical treatments mentioned previously were applied. As a result, all the treatments significantly reduced the O1s peak height on the AlGaIn surface as shown in **Fig. 3**. However, surface chemistry was very different. For the KOH- and HF-treated surfaces, surface stoichiometry was disturbed with Ga-rich and Al-rich features as well as appearance of K- and F- related residual XPS peaks, respectively. Such surfaces seem unfavorable due to possibilities of causing interfacial instabilities and unwanted reactions on deposition of metal contacts and insulating films during device processing.

On the other hand, the spectra after the NH_4OH treatment had no noticeable impurity peaks. They had almost stoichiometric Al-N and Ga-N bonding components from the following reasons. Namely, as shown in **Fig. 4 (a)**, the Al2p peak became shoulderless with a significant peak energy shift toward a lower binding energy after the NH_4OH treatment. This peak position is very close to that of the Al-N bond. The energy peak of the Ga3d spectra also moved to the position corresponding to the Ga-N bond. Furthermore, the data of integrated intensity ratios shown in **Fig. 4 (b)** indicated that this AlGaIn surface has a spatially uniform composition with a remarkable reduction of the O1s intensity. The Al composition was estimated to be 23% with reference to the Ga3d/N1s value in the reference GaN sample grown on sapphire by MOVPE, indicating that the NH_4OH -treated AlGaIn surface has a composition close to the stoichiometric value (25%). **Figure 5** shows the Raman spectra obtained

from the AlGaIn/GaN heterostructure samples exposed to air and treated in an NH_4OH solution. The NH_4OH treatment enhanced the intensity of the E_2 peak originating from the AlGaIn lattice, as shown in the inset, indicating that considerable improvement of the crystalline quality of the surface takes place by the NH_4OH treatment.

All these results indicate that the NH_4OH treatment is very effective in realizing an oxide-free and well-ordered AlGaIn surface.

Thermally oxidized AlGaIn surface

Properties of the surface obtained after intentional thermal oxidation of the NH_4OH -treated surface was further investigated. No noticeable N-related peaks were detected in both the XPS and AES spectra from such a surface. The XPS intensity ratios of the Al2p/O1s, Ga3d/O1s and Al2p/Ga3d are plotted in **Fig. 6** as a function of the escape angle. These ratios are almost constant in the depth direction at least down to escape depths of photoelectrons, indicating that the surface was covered with a much thicker oxide layer with spatially uniform composition distribution of Ga-oxide and Al-oxide components. The Al2p and Ga3d levels also have constant peak positions corresponding to those of Al_2O_3 and Ga_2O_3 , respectively. The composition of Al_2O_3 in the oxide layer was estimated to be 0.22, corresponding to the Al content in the AlGaIn bulk. This feature is very different from the surface natural oxide and provides a great hope for surface passivation by thermal oxidation.

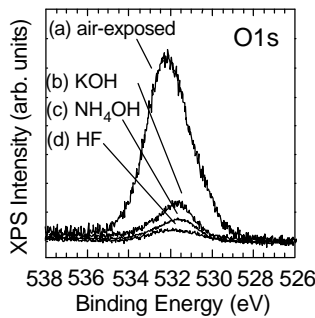


Fig. 3 O1s spectra of AlGaIn surfaces

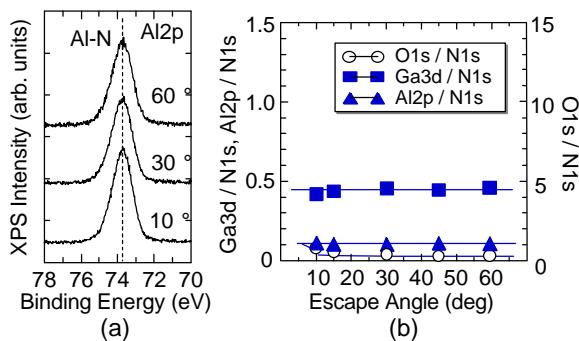


Fig. 4 (a) Angle-resolved XPS spectra and (b) the integrated intensity ratios from the NH_4OH -treated surfaces.

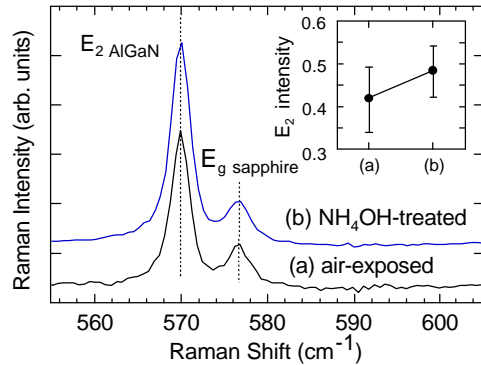


Fig. 5 The Raman spectra obtained from (a) exposed surface and (b) NH_4OH -treated surface.

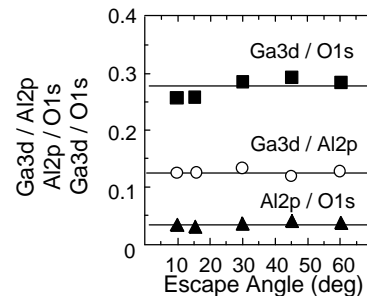


Fig. 6 The integrated intensity ratios after thermal oxidation for 30 min at 900 °C.